

HAT1127H

Silicon P Channel Power MOS FET Power Switching

REJ03G1330-0500 Rev.5.00 Jan 20, 2006

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Features

- Capable of -4.5 V gate drive
- Low drive current
- High density mounting
- $R_{DS(on)} = 3.6 \text{ m}\Omega \text{ typ. (at } V_{GS} = -10 \text{ V})$ • Ultra Low on-resistance

Outline

RENESAS Package code: PTZZ0005DA-A (Package name: LFPAK) Source Gate Drain

Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Drain to source voltage	V_{DSS}	-30	V
Gate to source voltage	V_{GSS}	-20/+10	V
Drain current	I_{D}	-40	А
Drain peak current	I _{D(pulse)} Note1	-160	Α
Body-drain diode reverse drain current	I_{DR}	-40	A
Channel dissipation	Pch Note2	30	W_ COM
Channel to Case Thermal Impedance	θch-c Note2	4.17	°C/W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1% WWW.DZSC.COM

2. $Tc = 25^{\circ}C$



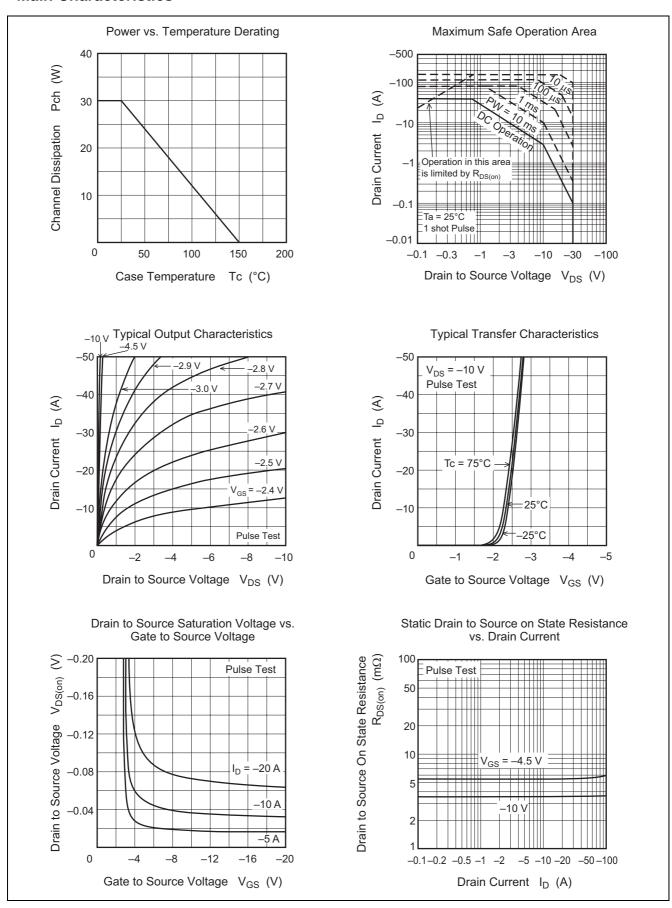
Electrical Characteristics

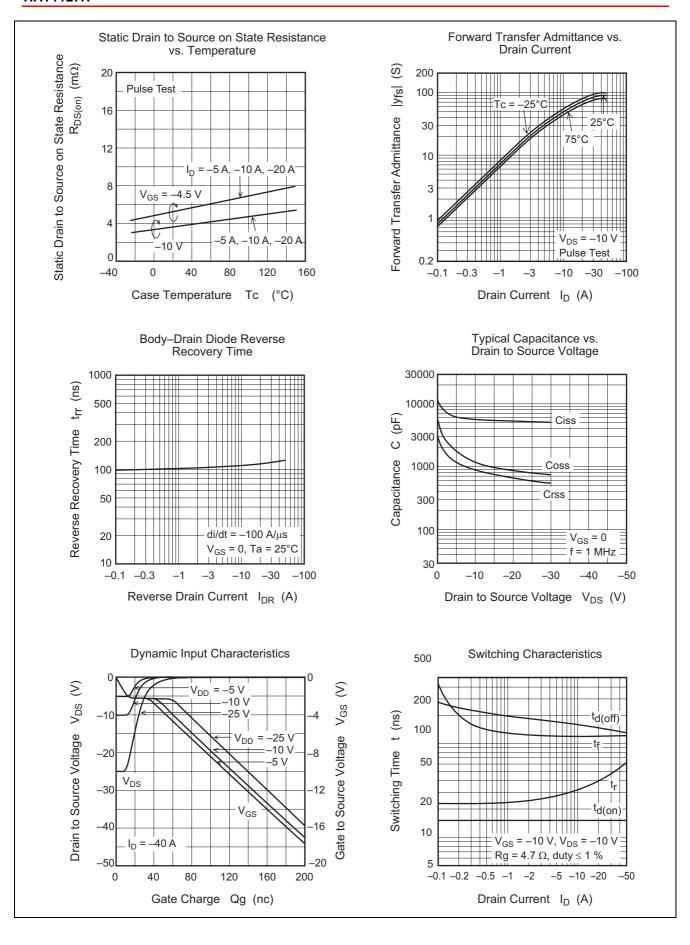
 $(Ta = 25^{\circ}C)$

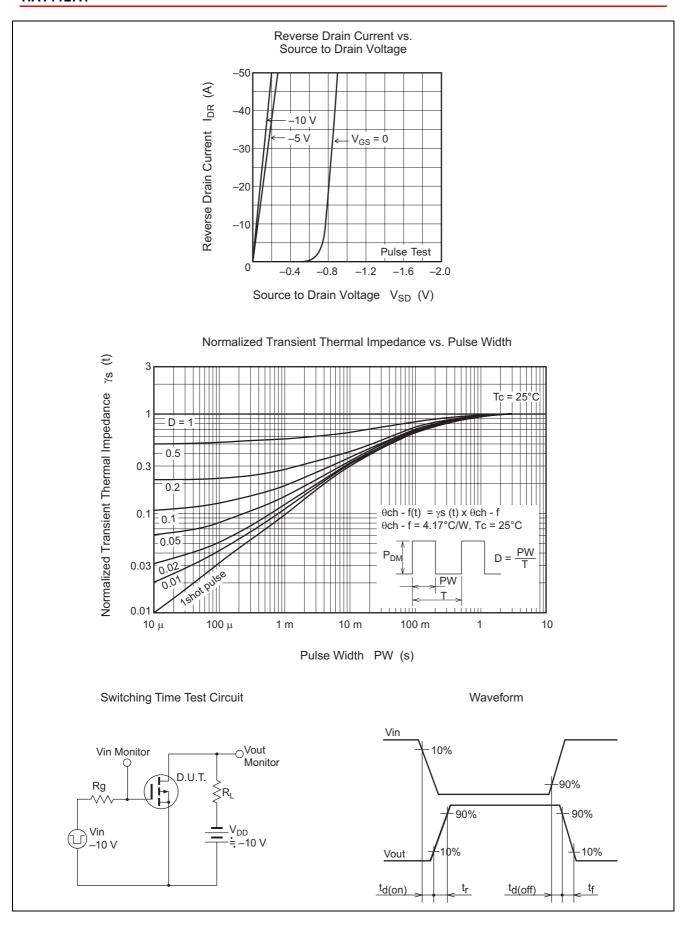
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V _{(BR)DSS}	-30	_	_	V	$I_D = -10 \text{ mA}, V_{GS} = 0$
Gate to source leak current	I _{GSS}	_	_	±0.1	μΑ	$V_{GS} = -20/+10 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	-1	μΑ	$V_{DS} = -30 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	-1.0	_	-2.5	V	$V_{DS} = -10 \text{ V}, I_D = -1 \text{ mA}$
Static drain to source on state	R _{DS(on)}	_	3.6	4.5	mΩ	$I_D = -20 \text{ A}, V_{GS} = -10 \text{ V}^{\text{Note3}}$
resistance	R _{DS(on)}	_	5.3	7.7	mΩ	$I_D = -20 \text{ A}, V_{GS} = -4.5 \text{ V}^{\text{Note3}}$
Forward transfer admittance	y _{fs}	40	70	_	S	$I_D = -20 \text{ A}, V_{DS} = -10 \text{ V}^{\text{Note3}}$
Input capacitance	Ciss	_	5600	_	pF	$V_{DS} = -10 \text{ V}, V_{GS} = 0,$
Output capacitance	Coss	_	1180	_	pF	f = 1 MHz
Reverse transfer capacitance	Crss	_	890	_	pF	
Total gate charge	Qg	_	125	_	nC	$V_{DD} = -10 \text{ V}, V_{GS} = -10 \text{ V},$ $I_{D} = -40 \text{ A}$
Gate to source charge	Qgs	_	15	_	nC	
Gate to drain charge	Qgd	_	28	_	nC	
Turn-on delay time	t _{d(on)}	_	25	_	ns	$V_{GS} = -10 \text{ V}, I_D = -20 \text{ A},$
Rise time	t _r	_	40	_	ns	$V_{DD} \cong -10 \text{ V}, \text{ R}_{L} = 0.5 \Omega,$ $\text{Rg} = 4.7 \Omega$
Turn-off delay time	t _{d(off)}	_	130	_	ns	
Fall time	t _f	_	115	_	ns	
Body-drain diode forward voltage	V_{DF}	_	-0.88	-1.15	V	$I_F = -40 \text{ A}, V_{GS} = 0^{\text{Note3}}$
Body–drain diode reverse recovery time	t _{rr}	_	120	_	ns	$I_F = -40 \text{ A}, V_{GS} = 0$ $di_F/dt = 100 \text{ A}/ \mu \text{s}$

Notes: 3. Pulse test

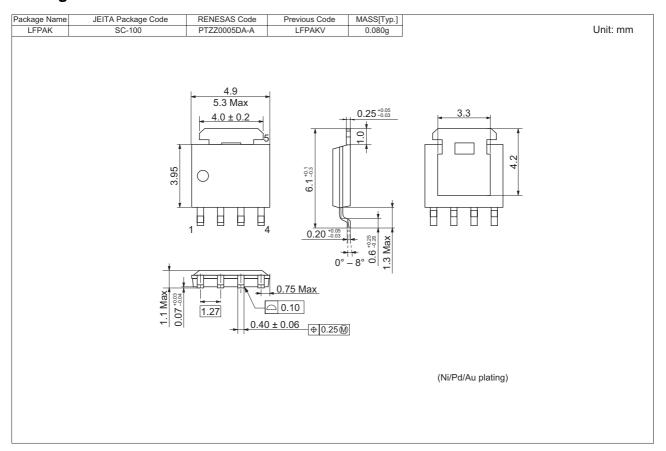
Main Characteristics







Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
HAT1127H-EL-E	2500 pcs	Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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